

Amendments to the Claims:

The following listing of claims will replace all prior versions and/or listings of claims in the application.

Listing of Claims:

1. (Currently Amended) An electronics assembly which comprises:
 - (i) an enclosure;
 - (ii) a plurality of heat-generating components located within the enclosure that are provided with heat-sinks; and
 - (iii) one or more fans for providing a flow of air through the enclosure for cooling the heat-generating components; the heat-generating components being located within the enclosure in line with the direction of the flow of air, and the heat-sinks having a configuration such that the air flows over the heat-sinks in parallel;
wherein at least one of the heat-sinks is mounted on one of the heat-generating components and has a cantilevered portion that extends over at least part of another of the heat-generating components.
2. (Currently amended) The ~~An~~ assembly as claimed in claim 1, which includes two such heat-generating components.
3. (Currently amended) The ~~An~~ assembly as claimed in claim 1, wherein each heat-sink is mounted on one of the heat-generating components, and wherein each has the ~~the~~ ~~[[a]]~~ cantilevered portion that extends over another ~~the or one other~~ of the heat-generating components but is not in contact therewith.

4. (Currently amended) The ~~An~~ assembly as claimed in claim 1, wherein each heat-sink has a plurality of cooling fins.

5. (Currently amended) The ~~An~~ assembly as claimed in claim 4, wherein the heat-generating components are mounted on a generally planar circuit board, and the fins are oriented generally perpendicular to the plane of the circuit board.

6. (Currently amended) The ~~An~~ assembly as claimed in claim 3, wherein each heat-sink has a plurality of cooling fins that are located on the cantilevered portion.

7. (Currently amended) The ~~An~~ assembly as claimed in claim 3, wherein each cantilevered portion extends over up to one half the transverse dimension of its associated heat-generating component in the direction of air flow.

8. (Currently amended) The ~~An~~ assembly as claimed in claim 2, wherein each heat-sink has a generally flat base that is mounted on its associated heat-generating component, and each heat-sink has the ~~the~~ [[a]] cantilevered portion that is provided with cooling fins and which extends over up to one half of a ~~the~~ transverse dimension of its associated heat-generating component in the direction of air flow, the cantilevered portion of each heat-sink extending over the base of the other heat-sink, and having a lower surface that is sufficiently higher than an ~~the~~ upper surface of the base to allow clearance between the cantilevered portion and the base of the other heat-sink.

9. (Currently amended) The ~~An~~ assembly as claimed in claim 2, wherein the heat-sinks are substantially identical, and each heat-sink is oriented at 180 degrees ~~180°~~ with respect to the other heat-sink.

10. (Currently amended) The An assembly as claimed in claim 1, wherein each heat-generating component generates substantially the same quantity of heat as the other heat-generating components ~~component~~.

11. (Currently amended) The An assembly as claimed in claim 1, wherein each heat-generating component is a microprocessor.

12. (Currently amended) The An assembly as claimed in claim 1, wherein the enclosure has a generally flat shape to allow the enclosure ~~it~~ to be stacked with one or more other such enclosures while allowing access to one or more side walls thereof.

13. (Currently amended) The An assembly as claimed in claim 12, ~~which~~ wherein the assembly is a rack-mounted assembly.

14. (Currently amended) The An assembly as claimed in claim 1, ~~which~~ wherein the assembly is a network server.

15. (Currently Amended) A method of cooling a plurality of heat-generating components in an electronics assembly, comprising ~~which comprises~~:

- (i) providing a heat-sink on each of the heat-generating components; and
- (ii) causing air to flow over the heat-sinks; the heat-generating components being located within an ~~the~~ enclosure in line with a ~~the~~ direction of the flow of air, and the heat-sinks having a configuration such that the air flows over the heat-sinks in parallel;

wherein at least one of the heat-sinks is mounted on one of the heat-generating components and has a cantilevered portion that extends over at least part of another of the heat-generating components.

16. (Currently amended) The [[A]] method as claimed in claim 15, wherein the heat-generating components are mounted on a generally planar circuit board, and air is caused to flow over the heat-sinks in a direction generally parallel to the plane of the circuit board.

17. (Original) A heat-sink for allowing cooling of a heat-generating electronics component, which comprises:

- (i) a generally flat base for mounting on the component; and
- (ii) a cantilevered portion having one end that is located on, and supported by, the base and another end that extends beyond the base, the cantilevered portion having a plurality of fins extending therealong to allow forced-air cooling of the heat-sink;

wherein the cantilevered portion extends over not more than one half of the base in a direction transverse to its length.

18. (Currently amended) The [[A]] heat-sink as claimed in claim 17, wherein the cantilevered portion has a lower edge that is higher than an ~~the~~ upper surface of the base.